

Title (en)
MULTI-SPLIT AIR CONDITIONER CAPABLE OF REFRIGERATING AND HEATING SIMULTANEOUSLY

Title (de)
MULTISPLIT-KLIMAANLAGE FÜR GLEICHZEITIGE KÜHL- UND HEIZOPERATIONEN

Title (fr)
CLIMATISEUR À DIVISIONS MULTIPLES APTE À RÉFRIGÉRER ET À CHAUFFER SIMULTANÉMENT

Publication
EP 2589889 A4 20140423 (EN)

Application
EP 11800068 A 20110310

Priority
• CN 201010214957 A 20100629
• CN 2011071673 W 20110310

Abstract (en)
[origin: EP2589889A1] Disclosed is a multi-split air conditioner capable of refrigerating and heating simultaneously. A heating circuit consists of a compressor(1), an oil-gas separator(2), a four-way valve(3), indoor heat exchanging systems(12,16,21,22), an outdoor heat exchanger(7), a four-way valve(3), and a gas-liquid separator(26) connected in series along the refrigerant flow direction. A refrigerating circuit consist of a compressor(1), an oil-gas separator(2), a four-way valve(3), an outdoor heat exchanger(7), indoor heat exchanging systems(12,16,21,22), and a gas-liquid separator(26) connected in series along the refrigerant flow direction. A parallel pipeline is arranged at a pipeline between the outdoor heat exchanger(7) and the indoor heat exchanging systems(12,16,21,22), and is utilized for connecting an second electronic expansion valve(8) with a second one-way valve(9) in parallel. A series pipeline is arranged with a third control valve(5) and a third one-way valve(6). An end of the series pipeline is connected to the pipeline between the four-way valve(3) and the outdoor heat exchanger(7), and another end of the series pipeline is connected to the pipeline between a first one-way valve(4) and the indoor exchanging systems(12,16,21,22). Five operation modes, i.e. single refrigerating, single heating, mainly refrigerating, mainly heating, simultaneous refrigerating and heating, can be realized in the multi-split air conditioner capable of refrigerating and heating simultaneously.

IPC 8 full level
F24F 3/06 (2006.01); **F25B 13/00** (2006.01); **F25B 30/02** (2006.01)

CPC (source: EP US)
F24F 3/065 (2013.01 - EP US); **F25B 13/00** (2013.01 - EP US); **F25B 30/02** (2013.01 - US); **F24F 2221/54** (2013.01 - EP US); **F25B 2313/0231** (2013.01 - EP US)

Citation (search report)
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• [I] US 2004035132 A1 20040226 - PARK JONG HAN [KR], et al
• [A] EP 1775527 A1 20070418 - DAIKIN IND LTD [JP]
• See references of WO 2012000323A1

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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 2589889 A1 20130508; EP 2589889 A4 20140423; CN 101865555 A 20101020; CN 101865555 B 20121003; US 2013213077 A1 20130822; WO 2012000323 A1 20120105

DOCDB simple family (application)
EP 11800068 A 20110310; CN 201010214957 A 20100629; CN 2011071673 W 20110310; US 201113807429 A 20110310